

Cypress Semiconductor Product Qualification Report

QTP#160407 VERSION *B
March 2019

Cypress Fab25 S8 Technology Qualification & PSoC4A S0 Family S8PF-10R, Fab25	
CY8C4013 CY8C4014	Programmable System-on-Chip (PSoC)

FOR ANY QUESTIONS ON THIS REPORT, PLEASE CONTACT
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PACKAGE/PRODUCT QUALIFICATION HISTORY

QTP Number	Description of Qualification Purpose	Date
151008	Qualification of S8* Technology in Fab25 Using TSG6M Device	Dec 2015
151403	Qualification of PSoC4A Device, S8PF-10R Technology in Fab25	Dec 2015
160407	Qualification of PSoC4A S0 Device, S8PF-10R Technology in Fab25	Dec 2015

PRODUCT DESCRIPTION (for qualification)	
Qualification Purpose: Qualification of PSoC4A S0 Device, S8PF-10R Technology in Fab25	
Marketing Part #:	CY8C4013 / CY8C4014
Device Description:	Programmable System-on-Chip (PSoC)
Cypress Division:	Cypress Semiconductor Corporation – MCU and Connectivity Division (MCD)

TECHNOLOGY/FAB PROCESS DESCRIPTION			
Number of Metal Layers:	Proprietary	Metal Composition:	Proprietary
Passivation Type and Thickness:			Proprietary
Generic Process Technology/Design Rule (μ -drawn):			Proprietary
Gate Oxide Material/Thickness (MOS):			Proprietary
Name/Location of Die Fab (prime) Facility:			Cypress, Fab 25
Die Fab Line ID/Wafer Process ID:			Fab25 / S8PF-10P

ALTERNATIVE FAB FACILITY SITE

FAB SITE	LOCATION	QTP NUMBER
Skywater	Minnesota , USA	132802
HHGrace Fab3	Shanghai, China	142304

MAJOR PACKAGE INFORMATION USED IN THIS QUALIFICATION

Package Designation:	LQ24A
Package Outline, Type, or Name:	QFN24L (4x4x0.6mm)
Mold Compound Name/Manufacturer:	GE 7470 / Nitto
Mold Compound Flammability Rating:	UL94 V-0
Mold Compound Alpha Emission Rate:	N/A (not low alpha mold compound)
Oxygen Rating Index: >28%	54%
Lead Frame Designation:	FMP
Lead Frame Material:	Pre-plated leadframe with base Copper
Substrate Material:	N/A
Lead Finish, Composition / Thickness:	NiPdAu
Die Backside Preparation Method/Metallization:	Backgrind
Die Separation Method:	Wafer Saw
Die Attach Supplier:	Henkel
Die Attach Material:	QMI-519
Bond Diagram Designation	001-88426
Wire Bond Method:	Thermosonic
Wire Material/Size:	CuPd / 0.8 mil (20um)
Package Cross Section Yes/No:	No
Assembly Process Flow:	001-87690M
Name/Location of Assembly (prime) facility:	CML-RA
MSL LEVEL	3
REFLOW PROFILE	260C

MAJOR PACKAGE INFORMATION USED IN THIS QUALIFICATION

Package Designation:	LQ16A
Package Outline, Type, or Name:	QFN16L (3x3x0.6mm)
Mold Compound Name/Manufacturer:	G700 / Sumitomo
Mold Compound Flammability Rating:	UL 94 V=0 pass
Mold Compound Alpha Emission Rate:	N/A (not low alpha mold compound)
Oxygen Rating Index: >28%	54%
Lead Frame Designation:	FMP
Lead Frame Material:	Copper with Ag-Spot Plating
Substrate Material:	N/A
Lead Finish, Composition / Thickness:	Pure Sn
Die Backside Preparation Method/Metallization:	Backgrind
Die Separation Method:	Wafer Saw
Die Attach Supplier:	Hitachi
Die Attach Material:	FH900
Bond Diagram Designation	001-88428
Wire Bond Method:	Thermosonic
Wire Material/Size:	CuPd / 0.8mil (20um)
Package Cross Section Yes/No:	No
Assembly Process Flow:	001-89390M
Name/Location of Assembly (prime) facility:	ASEK Taiwan (G)
MSL LEVEL	3
REFLOW PROFILE	260C

PACKAGE AVAILABILITY

PACKAGE	ASSEMBLY FACILITY SITE	WIRE	QTP NUMBER
16-Lead QFN 24-Lead QFN	CML-RA	CuPd	140804
16-Lead QFN 24-Lead QFN	ASE-K	CuPd	134505
16/24 -Lead QFN	UTL-UT	CuPd	141704
8-Lead SOIC	UTL-UT	CuPd	134513
16-Lead SOIC	UTL-UT	CuPd	134506

ELECTRICAL TEST / FINISH DESCRIPTION	
Test Location:	CML-RA, ASE-KH, UTAC-UT

RELIABILITY TESTS PERFORMED PER SPECIFICATION REQUIREMENTS

Stress/Test	Test Condition (Temp/Bias)	Result P/F
High Temperature Operating Life Early Failure Rate (EFR)	Dynamic Operating Condition, 150°C, 2.07V, 48 Hours JESD22-A-108-B	P
High Temperature Operating Life Latent Failure Rate (LFR)	Dynamic Operating Condition, 150°C, 2.07V, 500 Hours JESD22-A-108-B	P
Low Temperature Operating Life	-40°C	P
Endurance	Per datasheet, JESD22-A117	P
Data Retention	JESD22-A117 and JESD22-A103, 150C, 1000 Hours	P
Temperature Cycle	-65°C to 150°C, JESD22-A-104, 500 Cycles / 1000Cycles Precondition: JESD22 Moisture Sensitivity Level 3 192 Hrs, 30C/60%RH+3IR-Reflow, 260°C+0, -5°C	P
High Accelerated Saturation Test (HAST)	130C, 5.5V, 85%RH, JESD22-A-110-B, 96 Hours Precondition: JESD22 Moisture Sensitivity Level 3 192 Hrs, 30C/60%RH+3IR-Reflow, 260°C+0, -5°C	P
Pressure Cooker	121C/100%RH, JESD22-A102-C, 168 Hours Precondition: JESD22 Moisture Sensitivity Level 3 192 Hrs, 30C/60%RH+3IR-Reflow, 260°C+0, -5°C	P
Electrostatic Discharge Human Body Model (ESD-HBM)	2200V, 3300V, 4000V, 5000V, JESD22-A114E	P
Electrostatic Discharge Charge Device Model (ESD-CDM)	500V,750V, 1000V,1250V,1500V, 1750V JESD22-C101C	P
Static Latch-up	± 140mA, 125C/85°C, JESD78	P
Acoustic (M3)	J-STD-020	P

RELIABILITY FAILURE RATE SUMMARY

Stress/Test	Device Tested/ Device Hours	# Fails	Activation Energy	Thermal AF ³	Failure Rate
High Temperature Operating Life Early Failure Rate	1,469 Devices	0	N/A	N/A	0 PPM 1
High Temperature Operating Life Long Term Failure Rate	238,000	0	0.7	170	23 FIT 2

1. EFR devices number is based on QTP#151303 EFR data.
2. LFR device hours are based on QTP#151008, QTP#151403 and QTP#151303 LFR data.

- 1 Assuming an ambient temperature of 55°C and a junction temperature rise of 15°C.
- 2 Chi-squared 60% estimations used to calculate the failure rate.
- 3 Thermal Acceleration Factor is calculated from the Arrhenius equation

$$AF = \exp \left[\frac{E_A}{k} \left[\frac{1}{T_2} - \frac{1}{T_1} \right] \right]$$

where:

E_A = The Activation Energy of the defect mechanism.

K = Boltzmann's constant = 8.62×10^{-5} eV/Kelvin.

T_1 is the junction temperature of the device under stress and T_2 is the junction temperature of the device at use conditions.



Reliability Test Data

QTP #: 151008

Device	Fab Lot #	Assy Lot #	Assy Loc	Duration	Samp	Rej	Failure Mechanism
STRESS: ACOUSTIC, MSL3							
CYTT214032 (8CP206101)	4539372	611534008	CML-RA	COMP	15	0	
CYTT214032 (8CP206101)	4540145	611534709	CML-RA	COMP	15	0	
CY8C42452 (8CP44200)	4537464	611531543	CML-RA	COMP	15	0	
STRESS: DATA RETENTION, PLASTIC, 150C							
CYTT214032 (8CP206101)	4539372	611534008	CML-RA	500	80	0	
CYTT214032 (8CP206101)	4539372	611534008	CML-RA	1000	80	0	
CYTT214032 (8CP206101)	4540145	611534709	CML-RA	500	80	0	
CYTT214032 (8CP206101)	4540145	611534709	CML-RA	1000	80	0	
CY8C42452 (8CP44200)	4537464	611531543	CML-RA	500	80	0	
STRESS: DATA RETENTION, PLASTIC, 175C							
CYTT214032 (8CP206101)	4539372	611534008	CML-RA	76	80	0	
CYTT214032 (8CP206101)	4539372	611534008	CML-RA	152	79	0	
CYTT214032 (8CP206101)	4540145	611534709	CML-RA	76	80	0	
CYTT214032 (8CP206101)	4540145	611534709	CML-RA	152	80	0	
CY8C42452 (8CP44200)	4537464	611531543	CML-RA	76	80	0	
CY8C42452 (8CP44200)	4537464	611531543	CML-RA	152	80	0	
STRESS: HIGH TEMP DYNAMIC OPERATING LIFE-EARLY FAILURE RATE (150, 2.07V, Vcc Max)							
CYTT214032 (8CP206101)	4539372	611534008	CML-RA	48	1490	0	
CYTT214032 (8CP206101)	4540145	611534709	CML-RA	48	1510	0	
CYTT214032 (8CP206101)	4545249	611537364	CML-RA	48	1547	0	
STRESS: ENDURANCE							
CYTT214032 (8CP206101)	4539372	611534008	CML-RA	168	78	0	
CYTT214032 (8CP206101)	4539372	611534008	CML-RA	500	78	0	
CYTT214032 (8CP206101)	4540145	611534709	CML-RA	168	80	0	
CYTT214032 (8CP206101)	4540145	611534709	CML-RA	500	80	0	
CY8C42452 (8CP44200)	4537464	611531543	CML-RA	168	80	0	
CY8C42452 (8CP44200)	4537464	611531543	CML-RA	500	80	0	
STRESS: ESD-CHARGE DEVICE MODEL							
CYTT214032 (8CP206101)	4539372	611534008	CML-RA	500	9	0	
CYTT214032 (8CP206101)	4539372	611534008	CML-RA	750	3	0	
CYTT214032 (8CP206101)	4539372	611534008	CML-RA	1000	3	0	
CYTT214032 (8CP206101)	4539372	611534008	CML-RA	1250	3	0	
CYTT214032 (8CP206101)	4539372	611534008	CML-RA	1500	3	0	
CYTT214032 (8CP206101)	4539372	611534008	CML-RA	1750	3	0	



Reliability Test Data

QTP #: 151008

<i>Device</i>	<i>Fab Lot #</i>	<i>Assy Lot #</i>	<i>Assy Loc</i>	<i>Duration</i>	<i>Samp</i>	<i>Rej</i>	<i>Failure Mechanism</i>
STRESS: ESD-CHARGE DEVICE MODEL							
CYTT214032 (8CP206101)	4540145	611534709	CML-RA	500	9	0	
CYTT214032 (8CP206101)	4540145	611534709	CML-RA	750	3	0	
CYTT214032 (8CP206101)	4540145	611534709	CML-RA	1000	3	0	
CYTT214032 (8CP206101)	4540145	611534709	CML-RA	1250	3	0	
CYTT214032 (8CP206101)	4540145	611534709	CML-RA	1500	3	0	
CYTT214032 (8CP206101)	4540145	611534709	CML-RA	1750	3	0	
CY8C42452 (8CP44200)	4537464	611531543	CML-RA	500	9	0	
CY8C42452 (8CP44200)	4537464	611531543	CML-RA	750	3	0	
CY8C42452 (8CP44200)	4537464	611531543	CML-RA	1000	3	0	
CY8C42452 (8CP44200)	4537464	611531543	CML-RA	1250	3	0	
CY8C42452 (8CP44200)	4537464	611531543	CML-RA	1500	3	0	
CY8C42452 (8CP44200)	4537464	611531543	CML-RA	1750	3	0	
STRESS: ESD-HUMAN BODY MODEL PER JESD22, METHOD A114							
CYTT214032 (8CP206101)	4539372	611534008	CML-RA	1100	3	0	
CYTT214032 (8CP206101)	4539372	611534008	CML-RA	2200	8	0	
CYTT214032 (8CP206101)	4539372	611534008	CML-RA	3300	3	0	
CYTT214032 (8CP206101)	4539372	611534008	CML-RA	4000	3	0	
CYTT214032 (8CP206101)	4539372	611534008	CML-RA	5000	3	0	
CYTT214032 (8CP206101)	4540145	611534709	CML-RA	1100	3	0	
CYTT214032 (8CP206101)	4540145	611534709	CML-RA	2200	8	0	
CYTT214032 (8CP206101)	4540145	611534709	CML-RA	3300	3	0	
CYTT214032 (8CP206101)	4540145	611534709	CML-RA	4000	3	0	
CY8C42452 (8CP44200)	4537464	611531543	CML-RA	1100	3	0	
CY8C42452 (8CP44200)	4537464	611531543	CML-RA	2200	8	0	
CY8C42452 (8CP44200)	4537464	611531543	CML-RA	3300	3	0	
CY8C42452 (8CP44200)	4537464	611531543	CML-RA	4000	3	0	
STRESS: HI-ACCEL SATURATION TEST (130C, 85%RH, 5.5V), PRE COND 192 HR 30C/60%RH (MSL3)							
CYTT214032 (8CP206101)	4539372	611534008	CML-RA	96	30	0	
CYTT214032 (8CP206101)	4540145	611534709	CML-RA	96	30	0	
STRESS: HIGH TEMP DYNAMIC OPERATING LIFE-LATENT FAILURE RATE (150C, 2.07V, Vcc Max)							
CYTT214032 (8CP206101)	4539372	611534008	CML-RA	80	116	0	
CYTT214032 (8CP206101)	4539372	611534008	CML-RA	500	116	0	
CYTT214032 (8CP206101)	4540145	611534709	CML-RA	80	120	0	
CYTT214032 (8CP206101)	4540145	611534709	CML-RA	500	120	0	

Reliability Test Data

QTP #: 151008

<i>Device</i>	<i>Fab Lot #</i>	<i>Assy Lot #</i>	<i>Assy Loc</i>	<i>Duration</i>	<i>Samp</i>	<i>Rej</i>	<i>Failure Mechanism</i>
STRESS: LOW TEMPERATURE OPERATING LIFE, -40C							
CYTT214032 (8CP206101)	4539372	611534008	CML-RA	160	40	0	
CYTT214032 (8CP206101)	4539372	611534008	CML-RA	380	40	0	
STRESS: PRESSURE COOKER TEST (121C, 100%RH), 15 Psig, PRE COND 192 HR 30C/60%RH (MSL3)							
CYTT214032 (8CP206101)	4539372	611534008	CML-RA	168	75	0	
CYTT214032 (8CP206101)	4540145	611534709	CML-RA	168	78	0	
CY8C42452 (8CP44200)	4537464	611531543	CML-RA	168	80	0	
CY8C42452 (8CP44200)	4537464	611531543	CML-RA	288	80	0	
STRESS: PRE/POST LFR PARAMETER ASSESSMENT							
CYTT214032 (8CP206101)	4539372	611534008	CML-RA	COMP	10+2	0	
CYTT214032 (8CP206101)	4540145	611534709	CML-RA	COMP	10+2	0	
CY8C42452 (8CP44200)	4537464	611531543	CML-RA	COMP	10+2	0	
STRESS: STATIC LATCH-UP (85C, 140mA)							
CYTT214032 (8CP206101)	4539372	611534008	CML-RA	COMP	6	0	
CYTT214032 (8CP206101)	4540145	611534709	CML-RA	COMP	6	0	
CY8C42452 (8CP44200)	4537464	611531543	CML-RA	COMP	6	0	
STRESS: STATIC LATCH-UP (85C, 200mA)							
CYTT214032 (8CP206101)	4539372	611534008	CML-RA	COMP	3	0	
CYTT214032 (8CP206101)	4540145	611534709	CML-RA	COMP	3	0	
CY8C42452 (8CP44200)	4537464	611531543	CML-RA	COMP	3	0	
STRESS: STATIC LATCH-UP (85C, 300mA)							
CYTT214032 (8CP206101)	4539372	611534008	CML-RA	COMP	3	0	
CYTT214032 (8CP206101)	4540145	611534709	CML-RA	COMP	3	0	
CY8C42452 (8CP44200)	4537464	611531543	CML-RA	COMP	3	0	
STRESS: SEM CROSS SECTION							
CYTT214032 (8CP206101)	4539372	611534008	CML-RA	COMP	1	0	
STRESS: TC COND. C -65C TO 150C, PRE COND 192 HRS 30C/60%RH (MSL3)							
CYTT214032 (8CP206101)	4539372	611534008	CML-RA	500	80	0	
CYTT214032 (8CP206101)	4539372	611534008	CML-RA	1000	80	0	
CYTT214032 (8CP206101)	4540145	611534709	CML-RA	500	80	0	
CY8C42452 (8CP44200)	4537464	611531543	CML-RA	500	79	0	
CY8C42452 (8CP44200)	4537464	611531543	CML-RA	1000	79	0	
STRESS: THERMAL JUNCTION MEASUREMENT							
CYTT214032 (8CP206101)	4539372	611534008	CML-RA	COMP	1	0	



Reliability Test Data

QTP #: 151403

Device	Fab Lot #	Assy Lot #	Assy Loc	Duration	Samp	Rej	Failure Mechanism
STRESS: ACOUSTIC, MSL3							
CY8C42452A(8CP44200DB)	4537464	611531543	CML-R	COMP	15	0	
STRESS: DATA RETENTION, PLASTIC, 150C							
CY8C42452A(8CP44200DB)	4537464	611531543	CML-R	500	80	0	
STRESS: DATA RETENTION, PLASTIC, 175C							
CY8C42452A(8CP44200DB)	4537464	611531543	CML-R	76	80	0	
CY8C42452A(8CP44200DB)	4537464	611531543	CML-R	152	80	0	
STRESS: HIGH TEMP DYNAMIC OPERATING LIFE-EARLY FAILURE RATE (150C, 2.07V, Vcc Max)							
CY8C42452A(8CP44200DB)	4537464	611531543	CML-R	48	1510	0	
STRESS: ENDURANCE							
CY8C42452A(8CP44200DB)	4537464	611531543	CML-R	168	80	0	
CY8C42452A(8CP44200DB)	4537464	611531543	CML-R	500	80	0	
STRESS: ESD-CHARGE DEVICE MODEL							
CY8C42452A(8CP44200DB)	4537464	611531543	CML-R	500	9	0	
CY8C42452A(8CP44200DB)	4537464	611531543	CML-R	750	3	0	
CY8C42452A(8CP44200DB)	4537464	611531543	CML-R	1000	3	0	
CY8C42452A(8CP44200DB)	4537464	611531543	CML-R	1250	3	0	
CY8C42452A(8CP44200DB)	4537464	611531543	CML-R	1500	3	0	
CY8C42452A(8CP44200DB)	4537464	611531543	CML-R	1750	3	0	
CY8C42452A(8CP44200DB)	4537464	611531543	CML-R	2000	3	0	
STRESS: ESD-HUMAN BODY MODEL PER JESD22, METHOD A114							
CY8C42452A(8CP44200DB)	4537464	611531543	CML-R	1100	3	0	
CY8C42452A(8CP44200DB)	4537464	611531543	CML-R	2200	8	0	
CY8C42452A(8CP44200DB)	4537464	611531543	CML-R	3300	3	0	
CY8C42452A(8CP44200DB)	4537464	611531543	CML-R	4000	3	0	
STRESS: HIGH TEMP DYNAMIC OPERATING LIFE-LATENT FAILURE RATE (150C, 2.07V, Vcc Max)							
CY8C42452A(8CP44200DB)	4537464	611531543	CML-R	80	120	0	
CY8C42452A(8CP44200DB)	4537464	611531543	CML-R	500	120	0	
STRESS: PRESSURE COOKER TEST (121C, 100%RH), 15 Psig, PRE COND 192 HR 30C/60%RH (MSL3)							
CY8C42452A(8CP44200DB)	4537464	611531543	CML-R	168	80	0	
CY8C42452A(8CP44200DB)	4537464	611531543	CML-R	288	80	0	
STRESS: PRE/POST LFR PARAMETER ASSESSMENT							
CY8C42452A(8CP44200DB)	4537464	611531543	CML-R	COMP	10+2	0	
STRESS: STATIC LATCH-UP (85C, 140mA)							
CY8C42452A(8CP44200DB)	4537464	611531543	CML-R	COMP	6	0	
STRESS: STATIC LATCH-UP (85C, 200mA)							
CY8C42452A(8CP44200DB)	4537464	611531543	CML-R	COMP	3	0	
STRESS: STATIC LATCH-UP (125C, 140mA)							
CY8C42452A(8CP44200DB)	4537464	611531543	CML-R	COMP	3	0	

Reliability Test Data

QTP #: 151403

<i>Device</i>	<i>Fab Lot #</i>	<i>Assy Lot #</i>	<i>Assy Loc</i>	<i>Duration</i>	<i>Samp</i>	<i>Rej</i>	<i>Failure Mechanism</i>
STRESS: STATIC LATCH-UP (85C, 300mA)							
CY8C42452A(8CP44200DB)	4537464	611531543	CML-R	COMP	3	0	
STRESS: TC COND. C -65C TO 150C, PRE COND 192 HRS 30C/60%RH (MSL3)							
CY8C42452A(8CP44200DB)	4537464	611531543	CML-R	500	79	0	
CY8C42452A(8CP44200DB)	4537464	611531543	CML-R	1000	79	0	
STRESS: HIGH TEMP DYNAMIC OPERATING LIFE-EARLY FAILURE RATE (150C, 2.07V, Vcc Max)							
CY8C42452A(8CP44200DB)	4537464	611531543	CML-R	48	1469	0	



Reliability Test Data

QTP #: 160407

Device	Fab Lot #	Assy Lot #	Assy Loc	Duration	Samp	Rej	Failure Mechanism
STRESS: ACOUSTIC, MSL3							
CY8C4013 (8CP44304)	4542914	611534639	CML-RA	COMP	15	0	
STRESS: DATA RETENTION, PLASTIC, 150C							
CY8C4013 (8CP44304)	4542914	611534639	CML-RA	500	80	0	
STRESS: DATA RETENTION, PLASTIC, 175C							
CY8C4013 (8CP44304)	4542914	611534639	CML-RA	76	80	0	
CY8C4013 (8CP44304)	4542914	611534639	CML-RA	152	80	0	
STRESS: HIGH TEMP DYNAMIC OPERATING LIFE-EARLY FAILURE RATE (150C, 2.07V, Vcc Max)							
CY8C4013 (8CP44303CB)	4542914	611534693	ASE-G	48	1469	0	
STRESS: ENDURANCE							
CY8C4013 (8CP44303CB)	4542914	611534693	ASE-G	168	80	0	
CY8C4013 (8CP44303CB)	4542914	611534693	ASE-G	500	80	0	
STRESS: ESD-CHARGE DEVICE MODEL							
CY8C4013 (8CP44304)	4542914	611534639	CML-RA	500	9	0	
CY8C4013 (8CP44304)	4542914	611534639	CML-RA	750	3	0	
CY8C4013 (8CP44304)	4542914	611534639	CML-RA	1000	3	0	
CY8C4013 (8CP44304)	4542914	611534639	CML-RA	1250	3	0	
CY8C4013 (8CP44304)	4542914	611534639	CML-RA	1500	3	0	
CY8C4013 (8CP44304)	4542914	611534639	CML-RA	1750	3	0	
STRESS: ESD-HUMAN BODY MODEL PER JESD22, METHOD A114							
CY8C4013 (8CP44304)	4542914	611534639	CML-RA	1100	3	0	
CY8C4013 (8CP44304)	4542914	611534639	CML-RA	2200	8	0	
CY8C4013 (8CP44304)	4542914	611534639	CML-RA	3300	3	0	
CY8C4013 (8CP44304)	4542914	611534639	CML-RA	4000	3	0	
CY8C4013 (8CP44304)	4542914	611534639	CML-RA	5000	3	0	
CY8C4013 (8CP44304)	4542914	611534639	CML-RA	6000	3	0	
CY8C4013 (8CP44304)	4542914	611534639	CML-RA	7000	3	0	
STRESS: HIGH TEMP DYNAMIC OPERATING LIFE-LATENT FAILURE RATE (150C, 2.07V, Vcc Max)							
CY8C4013 (8CP44303CB)	4542914	611534693	ASE-G	80	120	0	
CY8C4013 (8CP44303CB)	4542914	611534693	ASE-G	500	120	0	
STRESS: PRESSURE COOKER TEST (121C, 100%RH), 15 Psig, PRE COND 192 HR 30C/60%RH (MSL3)							
CY8C4013 (8CP44304)	4542914	611534639	CML-RA	168	80	0	
CY8C4013 (8CP44304)	4542914	611534639	CML-RA	288	79	0	
STRESS: PRE/POST LFR PARAMETER ASSESSMENT							
CY8C4013 (8CP44303CB)	4542914	611534693	ASE-G	COMP	10+2	0	

Reliability Test Data

QTP #: 160407

<i>Device</i>	<i>Fab Lot #</i>	<i>Assy Lot #</i>	<i>Assy Loc</i>	<i>Duration</i>	<i>Samp</i>	<i>Rej</i>	<i>Failure Mechanism</i>
STRESS: STATIC LATCH-UP (85C, 140mA)							
CY8C4013 (8CP44304)	4542914	611534639	CML-RA	COMP	6	0	
STRESS: STATIC LATCH-UP (85C, 200mA)							
CY8C4013 (8CP44304)	4542914	611534639	CML-RA	COMP	3	0	
STRESS: STATIC LATCH-UP (125C, 140mA)							
CY8C4013 (8CP44304)	4542914	611534639	CML-RA	COMP	3	0	
STRESS: STATIC LATCH-UP (85C, 300mA)							
CY8C4013 (8CP44304)	4542914	611534639	CML-RA	COMP	3	0	
STRESS: TC COND. C -65C TO 150C, PRE COND 192 HRS 30C/60%RH (MSL3)							
CY8C4013 (8CP44304)	4542914	611534639	CML-RA	500	80	0	
CY8C4013 (8CP44304)	4542914	611534639	CML-RA	1000	80	0	



Document History Page

Document Title: QTP#160407: Cypress Fab25 S8 Technology Qualification & PSoC4A S0 Family S8PF-10R, Fab25
Document Number: 002-11051

Rev.	ECN No.	Orig. of Change	Description of Change
**	5121399	HSTO	Initial Spec Release
*A	5158714	HSTO	Update MPN list
*B	6525539	HSTO	Update Cypress Logo Update Contact Person (Reliability Director / Manager) Update "TECHNOLOGY/FAB PROCESS DESCRIPTION" table Update "MAJOR PACKAGE INFORMATION USED IN THIS QUALIFICATION" table Replaced "Fab4/CMI" with Skywater